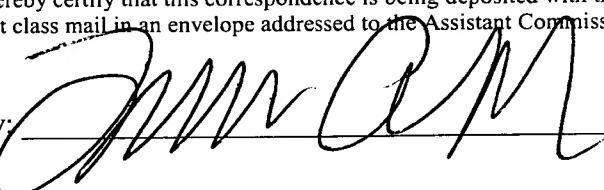


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Docket No.: GR 99 P 2591

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By: 

Date: August 29, 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Gerald Debey et al.
Applic. No. : 09/838,743 ✓
Filed : April 19, 2001
Title : Vertically structured power semiconductor component
Group Art Unit : 2811

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PRELIMINARY AMENDMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D. C. 20231

Sir:

Preliminary to examination, kindly amend the above-identified application as follows:

In the Abstract:

On page 29, replace the entire paragraph with the following paragraph:

A vertically structured semiconductor power component is described. A layer thickness of a substrate of the power module between a pn junction and a metallized back is chosen in such a manner that a space charge region produced in the semiconductor component extends as far as the back when a blocking voltage between a source and a drain electrode is applied before a field strength produced by the applied blocking voltage reaches a critical value.